



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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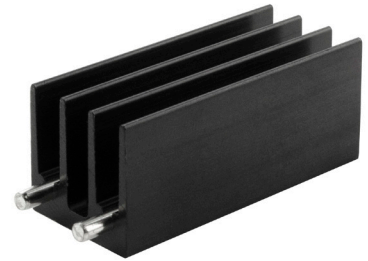




**SERIES:** HSE-BX-04H | **DESCRIPTION:** HEAT SINK

**FEATURES**

- TO-220 or TO-218 package
- placement pins for secure PCB attachment
- round hole for component attachment
- multiple available cut lengths



**MODEL**

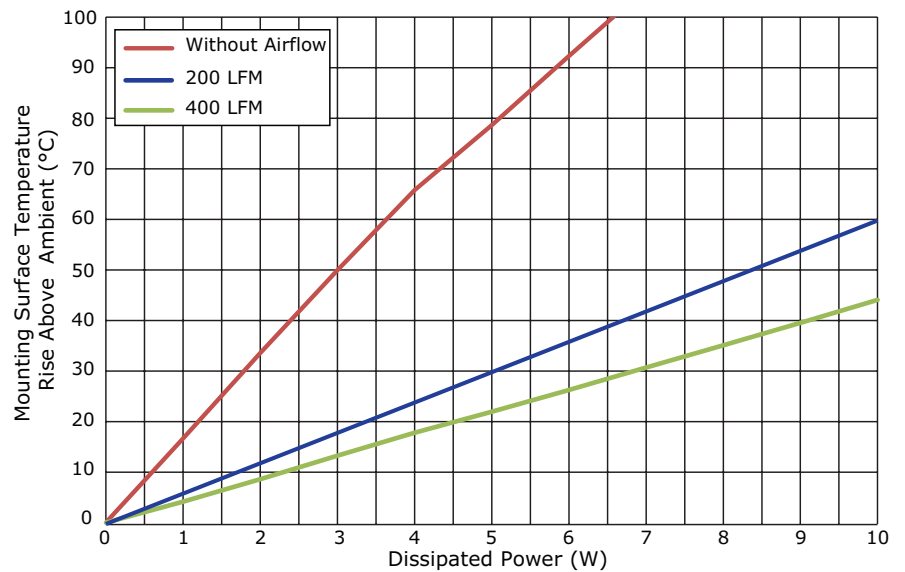
	length (mm)	thermal resistance <sup>1</sup>			power dissipation <sup>1</sup> @ 75°C ΔT, nat conv (W)	
		@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)		@ 1 W, 400 LFM (°C/W)
HSE-B254-04H	25.4	15.96	16.65	4.93	4.13	4.70
HSE-B381-04H	38.1	12.71	12.33	4.44	2.57	5.90

Note: 1. See performance curves for full thermal resistance details.  
2. Custom cut to length options available. Thermal data not available on custom lengths.

**PERFORMANCE CURVES**

**HSE-B254-04H**

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T <sub>hs</sub> - T <sub>a</sub> ) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	16.65	4.93	4.13
2	33.54	11.08	8.61
3	49.96	17.20	13.23
4	65.78	23.50	17.80
5	78.65	29.14	21.94
6	92.33	35.03	26.22
7	105.77	41.10	30.69
8	117.14	46.59	35.07
9	127.85	53.10	39.55
10	137.37	59.79	44.08

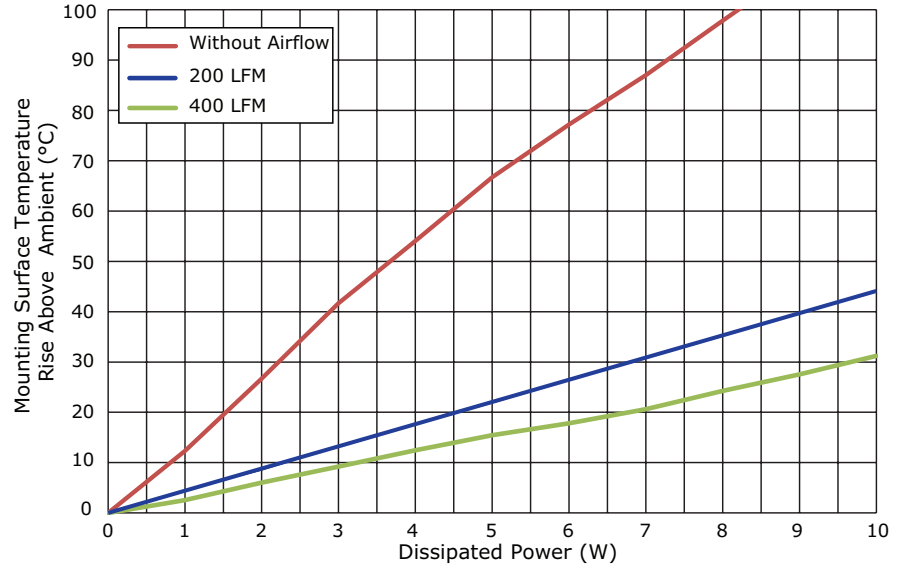


T<sub>hs</sub>: "hot spot" temperature measured on the heatsink  
T<sub>a</sub>: ambient temperature

## PERFORMANCE CURVES (CONTINUED)

### HSE-B381-04H

Power (W)	Heatsink Temperature Rise Above Ambient ( $\Delta T = T_{hs} - T_a$ ) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	12.33	4.44	2.57
2	26.70	8.40	6.04
3	41.68	13.14	9.20
4	54.04	17.42	12.44
5	66.70	21.73	15.45
6	77.18	26.26	17.85
7	86.99	30.62	20.63
8	97.85	35.10	24.27
9	108.50	39.48	27.54
10	117.17	44.10	31.21

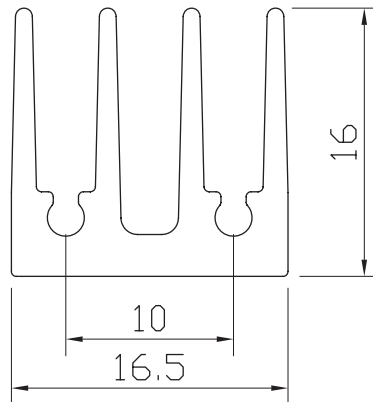
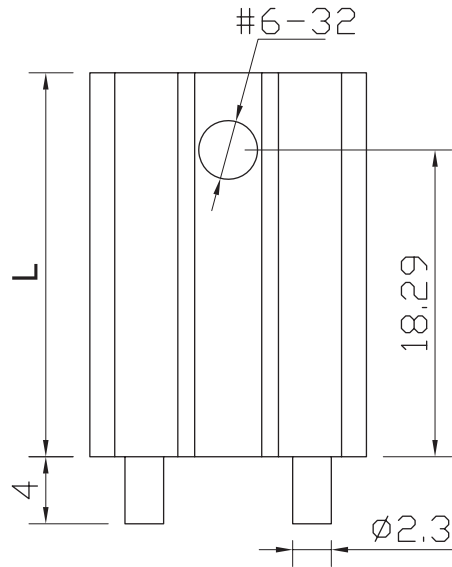


$T_{hs}$ : "hot spot" temperature measured on the heatsink  
 $T_a$ : ambient temperature

## MECHANICAL DRAWING

units: mm  
tolerance: ±0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
PIN MATERIAL	steel
PIN PLATING	tin



MODEL NO.	LENGTH, L (mm)	WEIGHT (g)
HSE-B254-04H	25.4	9.5
HSE-B381-04H	38.1	15.4

## REVISION HISTORY

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rev.	description	date
1.0	initial release	04/26/2017

The revision history provided is for informational purposes only and is believed to be accurate.



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